

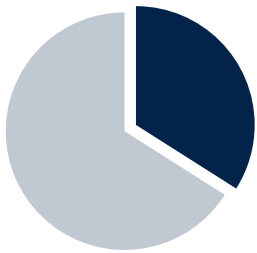


**Capital  
Markets  
Day 2022**

# **Automotive and Discrete Group**

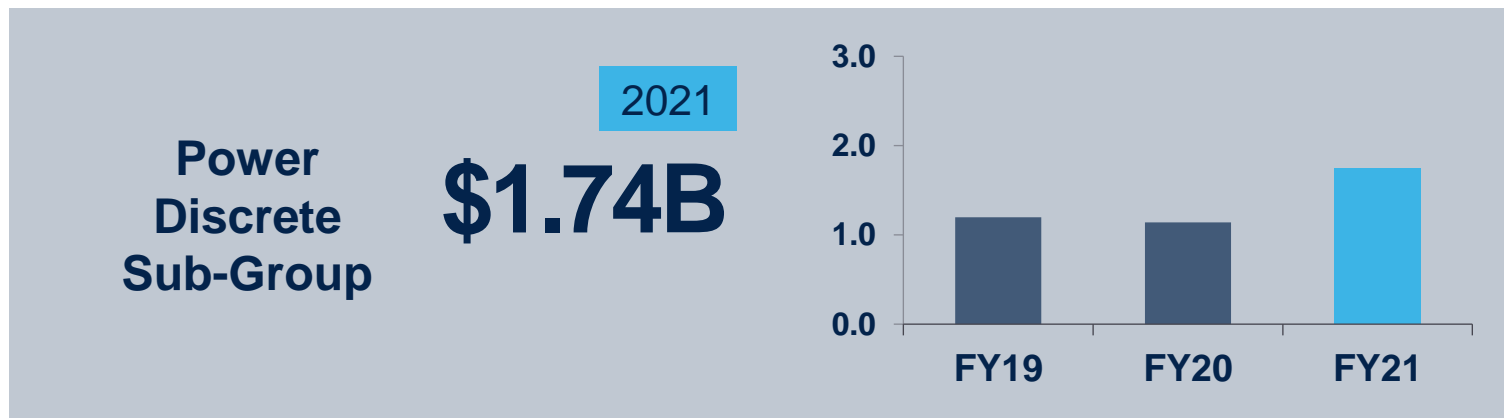
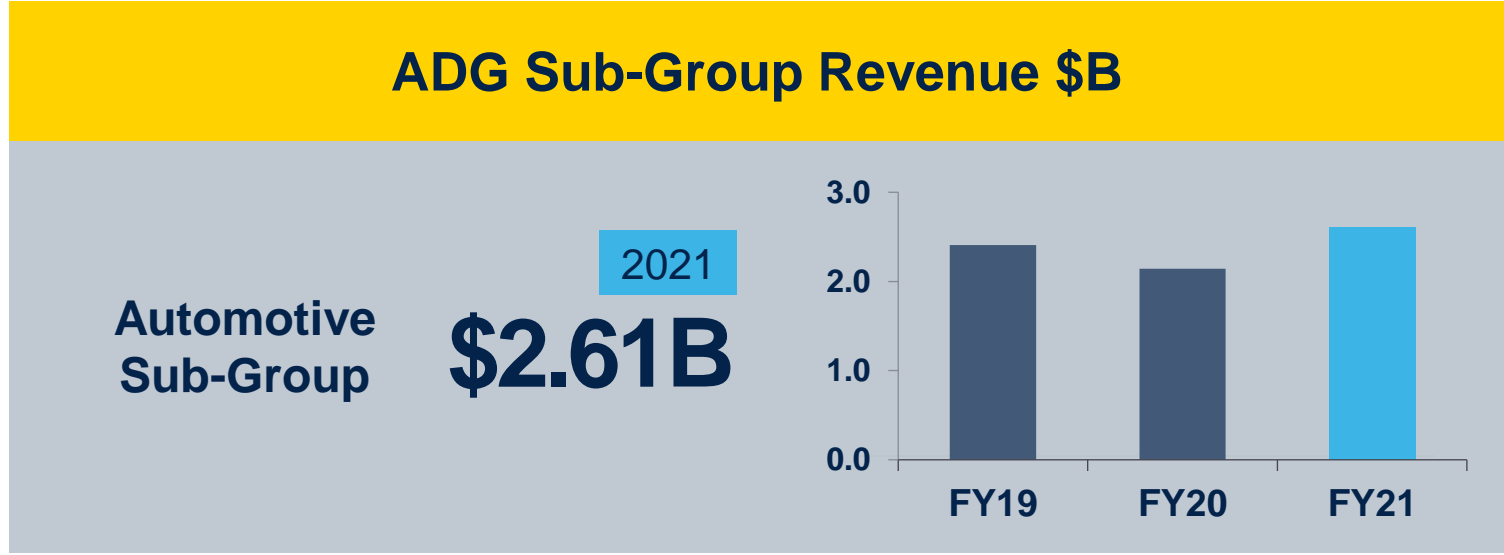
**Marco Monti**

President, Automotive and Discrete Group



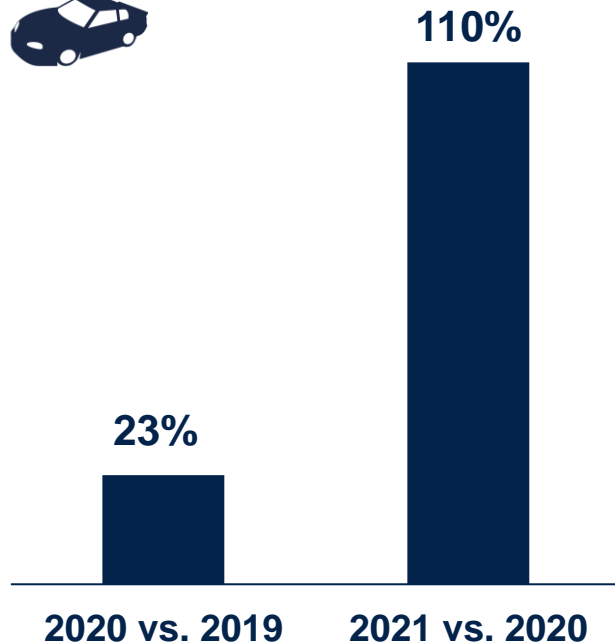
34% of ST FY21 Revenues

# Revenue overview - ADG

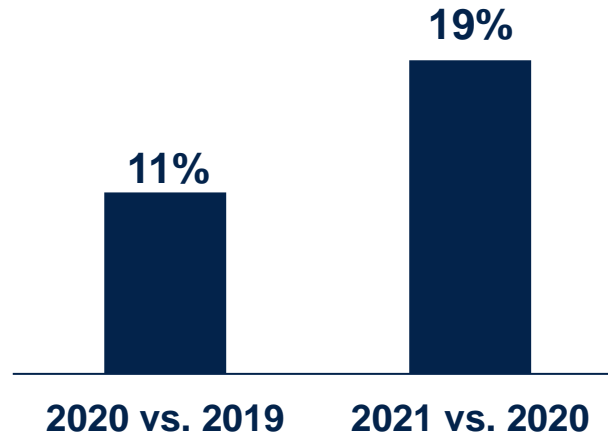


# ADG revenue expansion driven by strong growth in new automotive trends

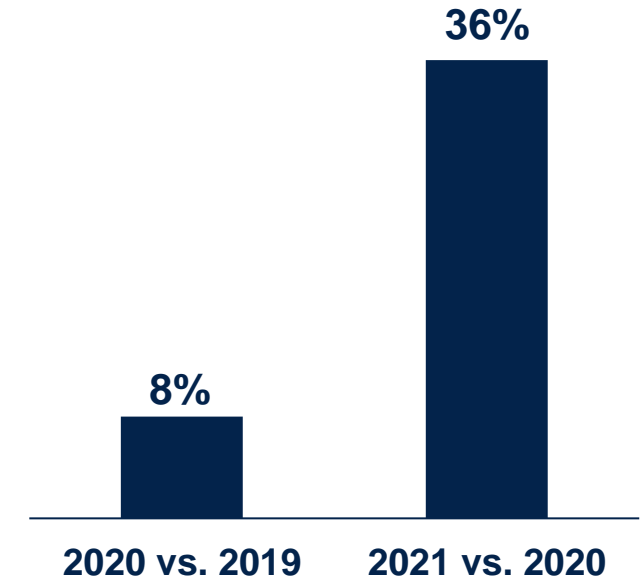
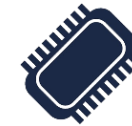
## Car electrification



## ADAS systems



## 32-bit automotive MCUs





# ADG addresses ST's four end markets

Automotive



**~70%**



Continue to reinforce leadership

Industrial



**~23%**



Further expansion

Personal Electronics



**~7%**



Focus on product Innovation

Communications Equipment, Computers & Peripherals

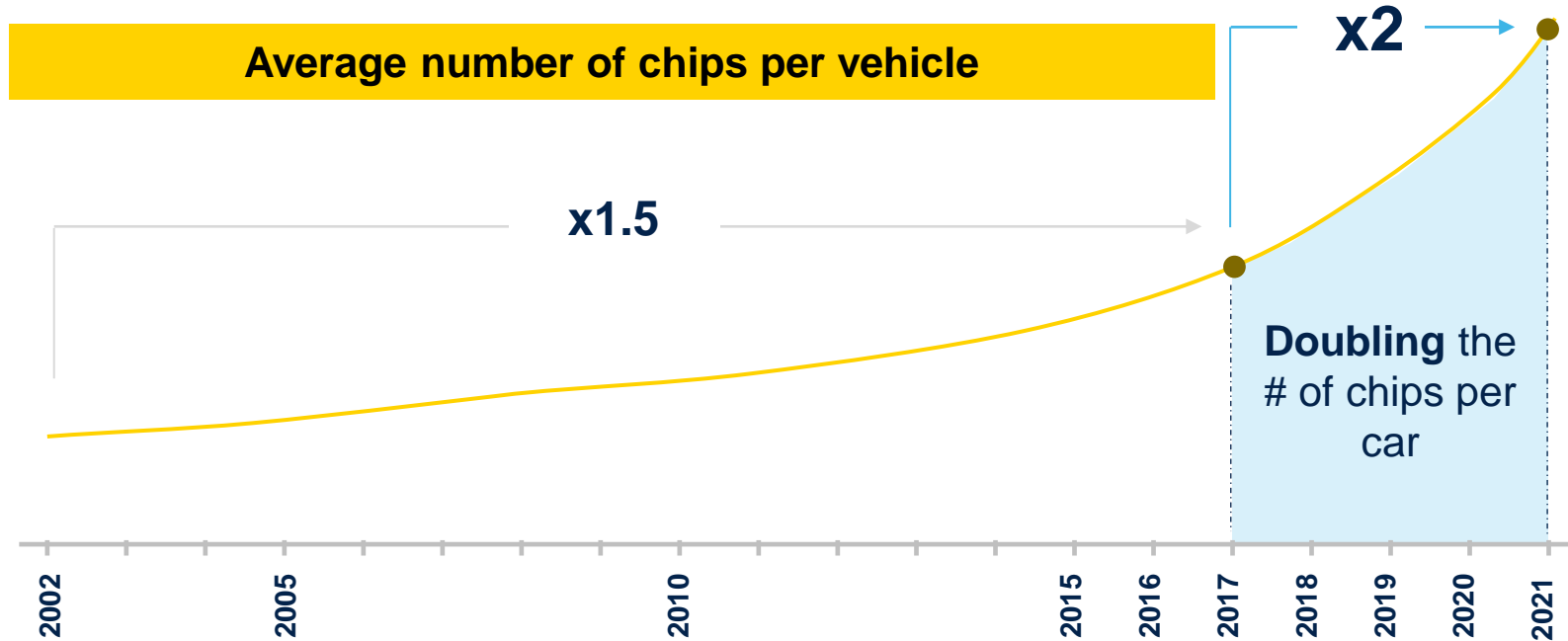


New partnerships for fast growing growth on emerging markets

**% of ADG revenues 2021**

# Acceleration of silicon content pervasion in automotive

Semiconductor content per car steadily increased over the two past decades and strongly accelerated recently



Automotive **electronics demand** continuously rising, confirming secular trends



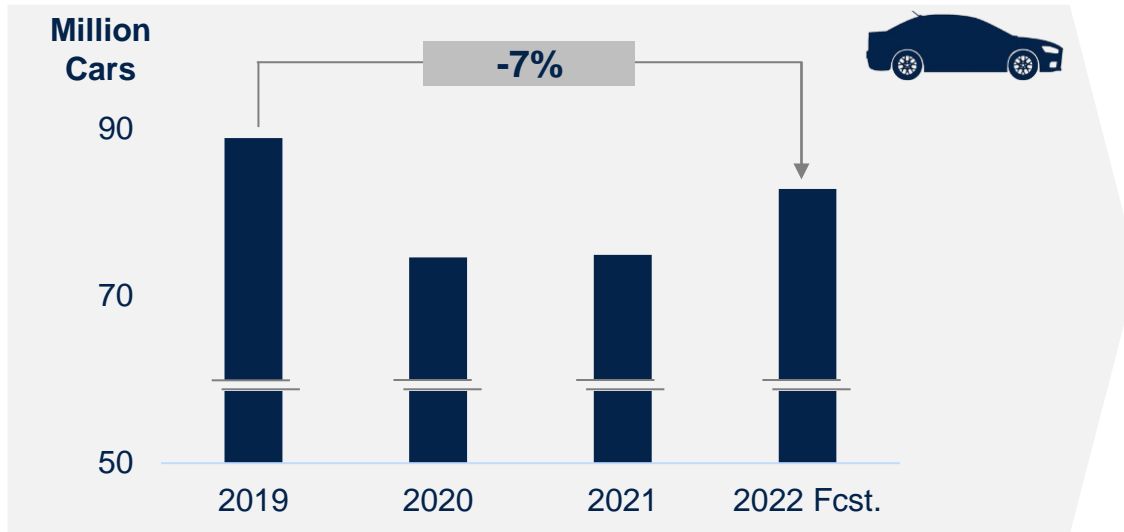
Average number of automotive **chips per car** accelerated in last 4 years



Expectation for further **acceleration** in the **next few years**

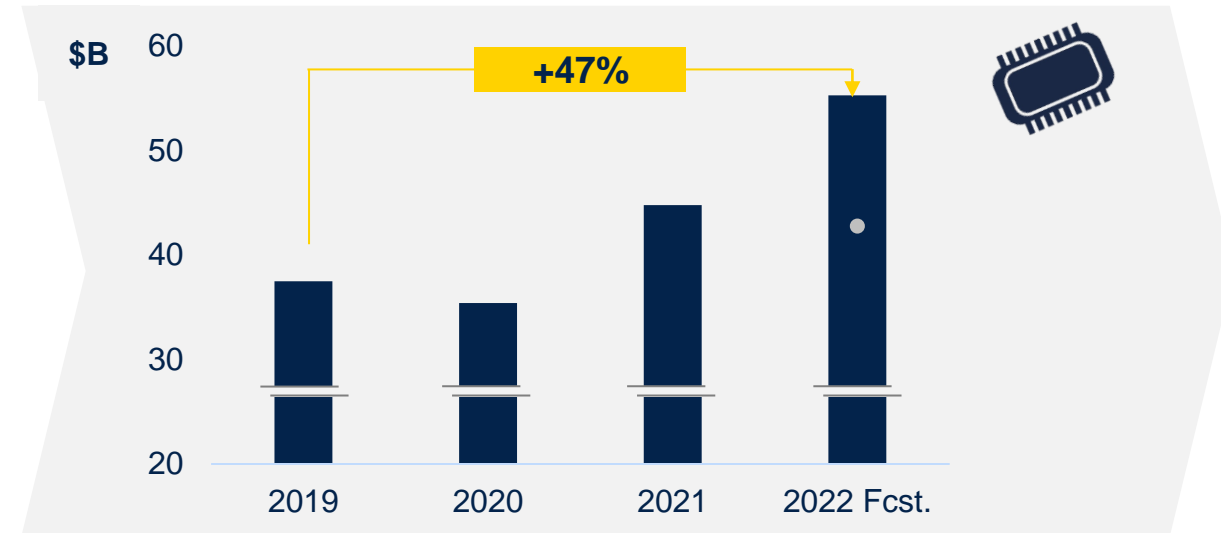
# Automotive semiconductor demand has become uncorrelated with car production

## Global light vehicle production

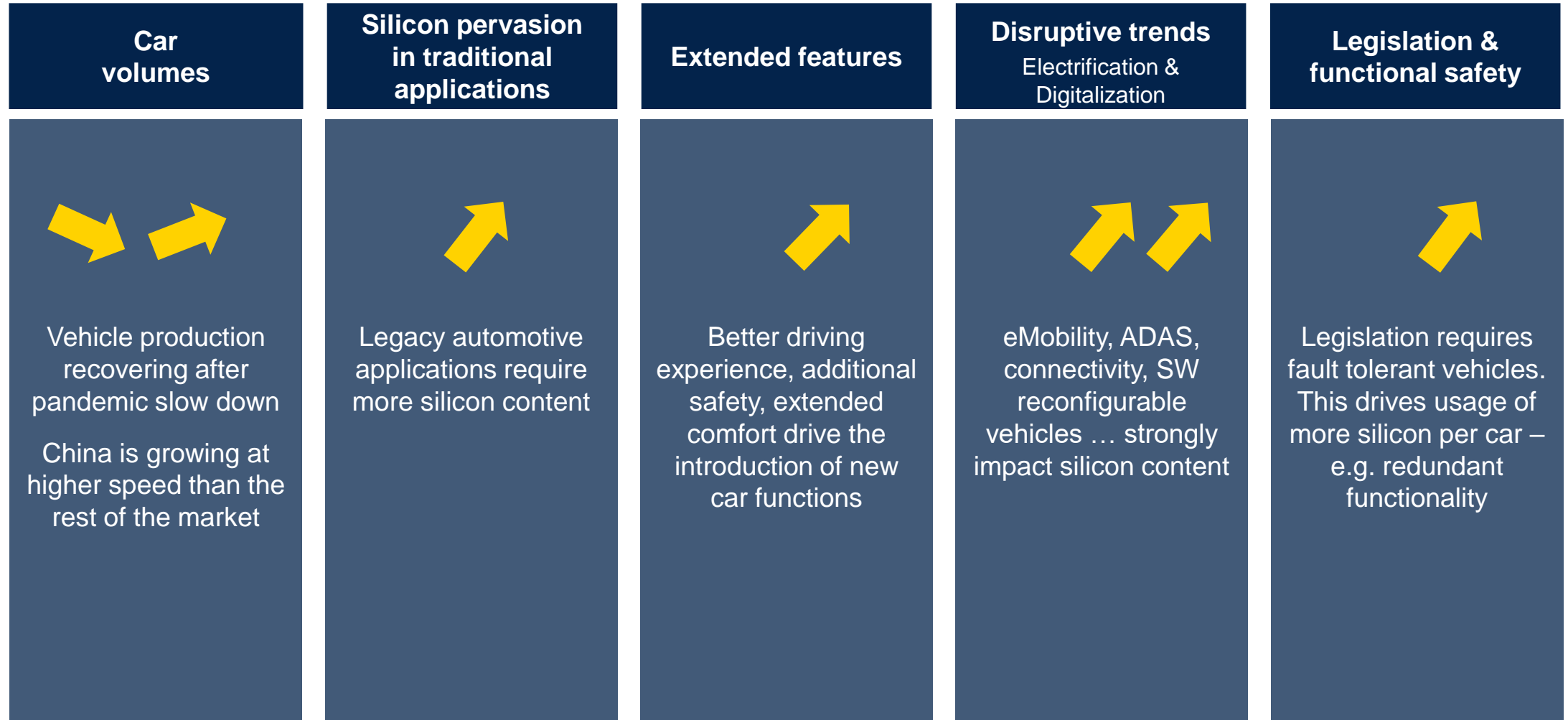


Production rate struggling to return to pre-pandemic levels

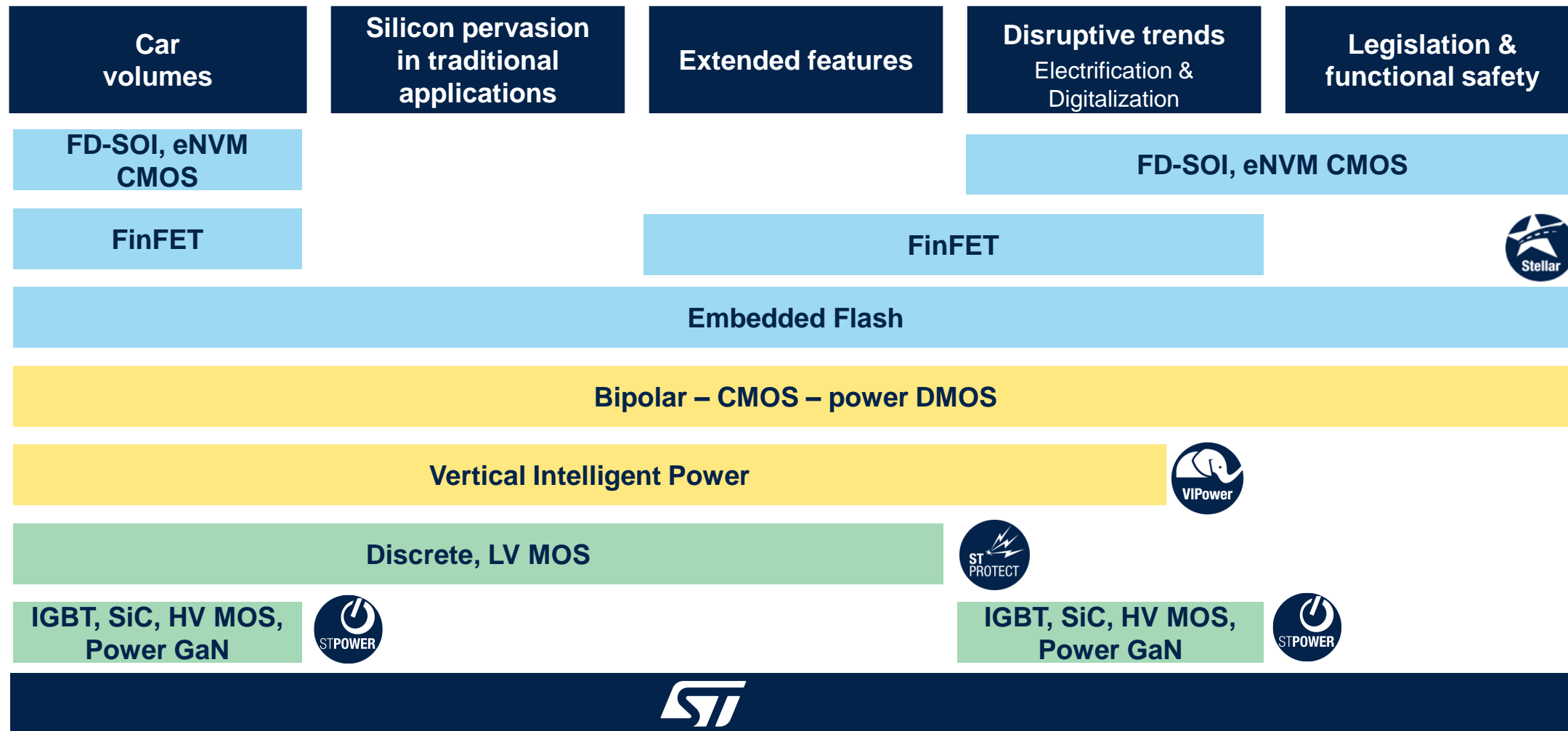
## Automotive semiconductor TAM



# Multiple positive trends driving increasing automotive semiconductor content



# ST has the portfolio of differentiated technologies needed to serve new automotive requirements





# Silicon content increasing in traditional applications

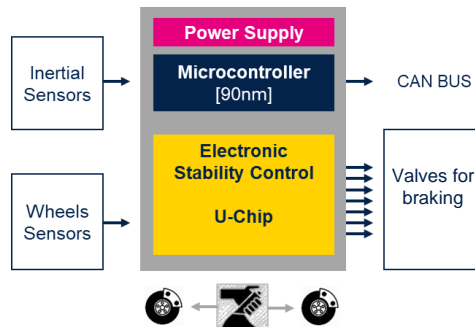
The same Electronic Stability Control functionality requires additional and more complex ICs

...2018

2022

Next Gen

MCU: Single core; 120MHz; 1Mb



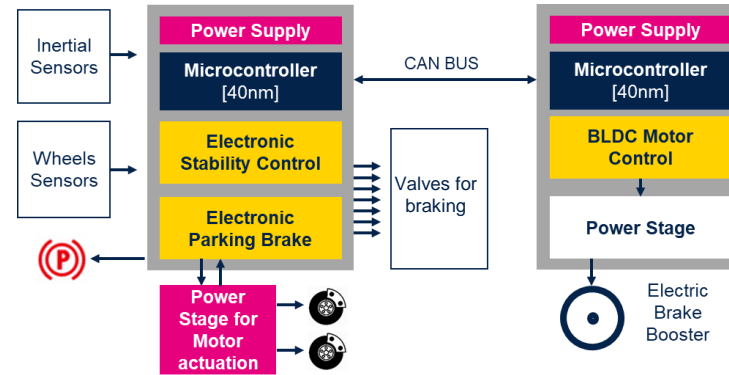
1 ECU; ~3 ICs



\*EPB: Electric Parking Brake

EPB\* penetration: ~30%

MCU: Dual core; 300MHz; 4-8Mb

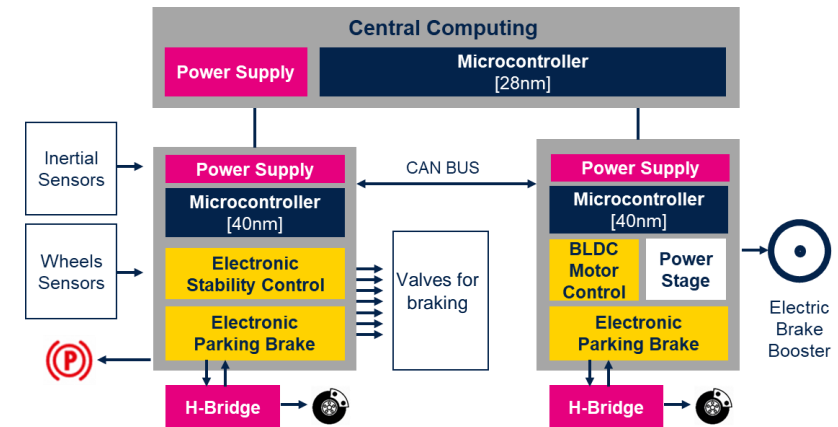


2 ECU; ~9 ICs



>50%

MCU: Triple core; 400MHz; 6-8Mb



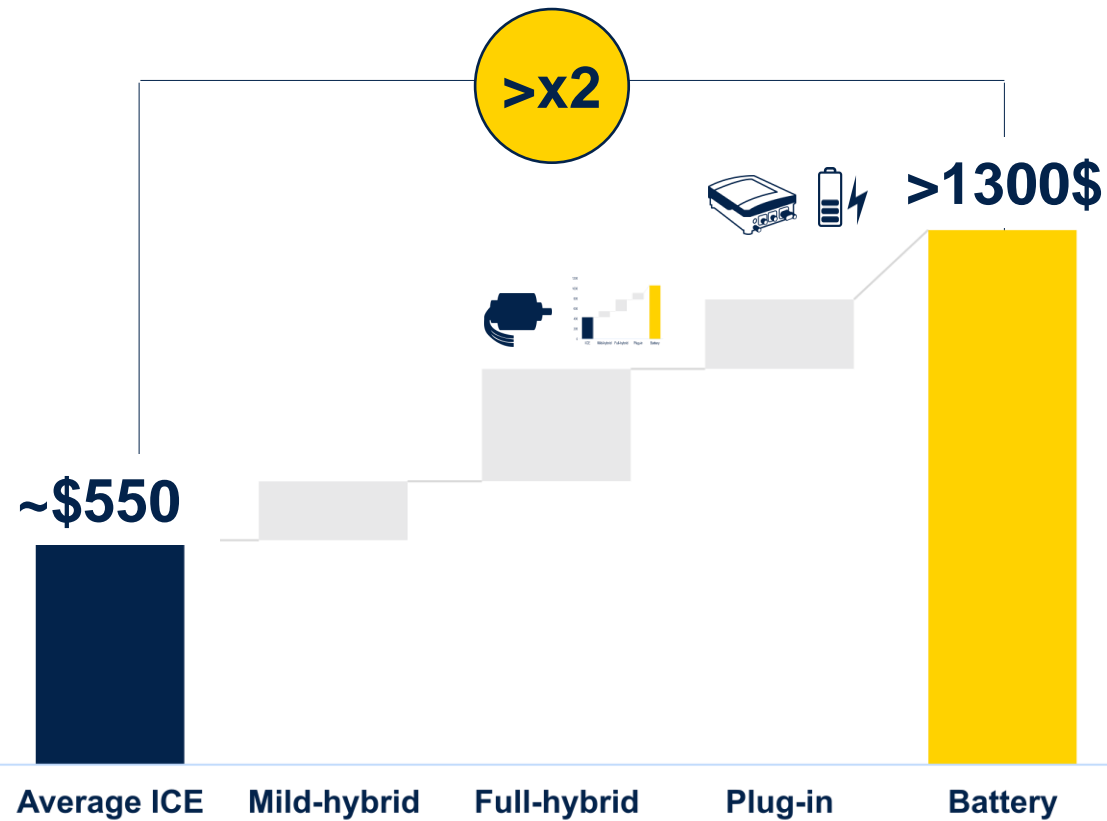
3 ECU; ~13 ICs



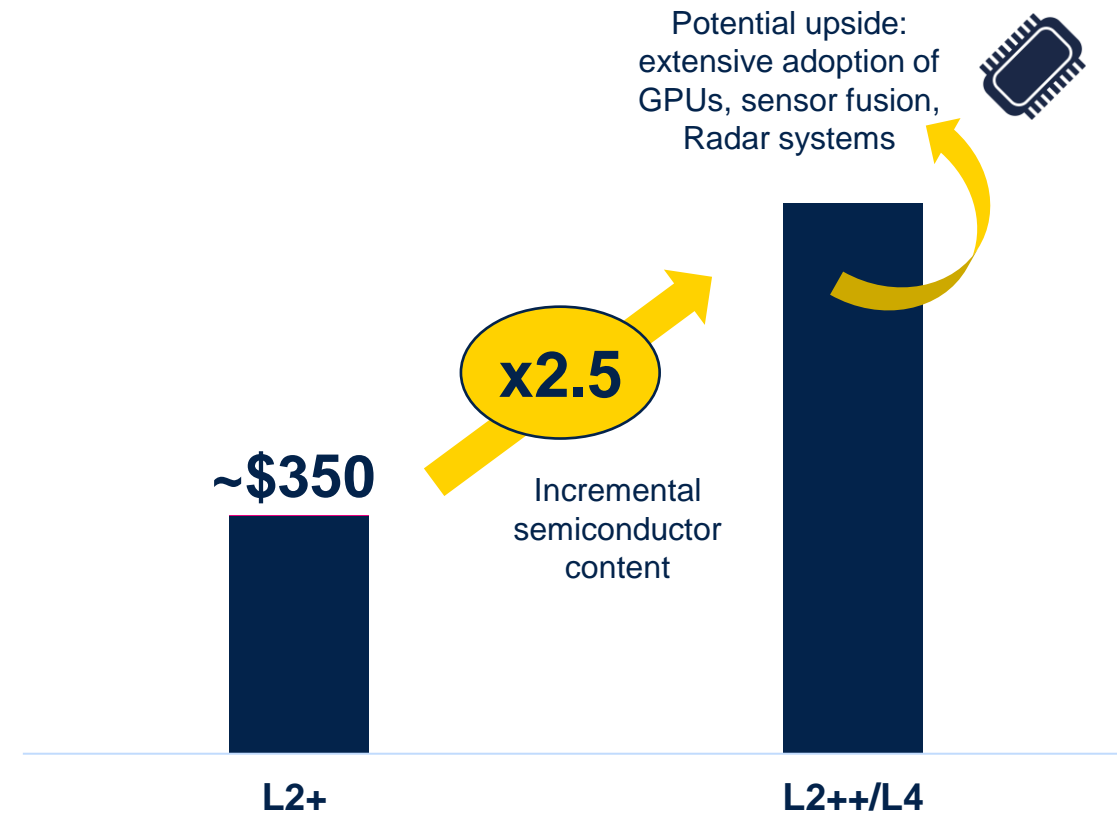
>70%

# Electrification and digitalization drive disruptive increase in silicon content

Electrification significantly increases car silicon content



To increase autonomy additional silicon is needed in every car

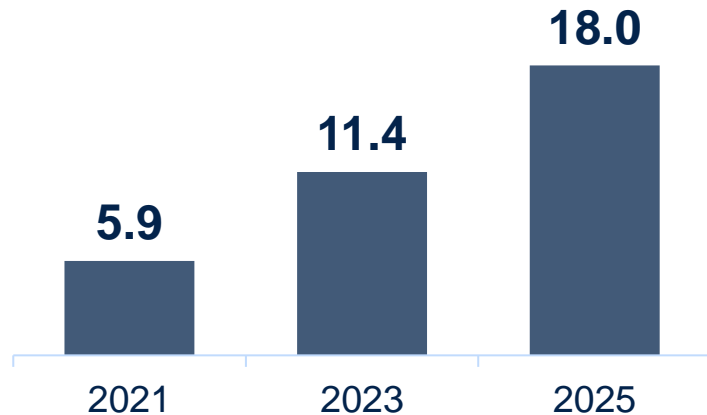


# New automotive trends drive semiconductor TAM

## Electrification



**+32%**  
CAGR 21-25

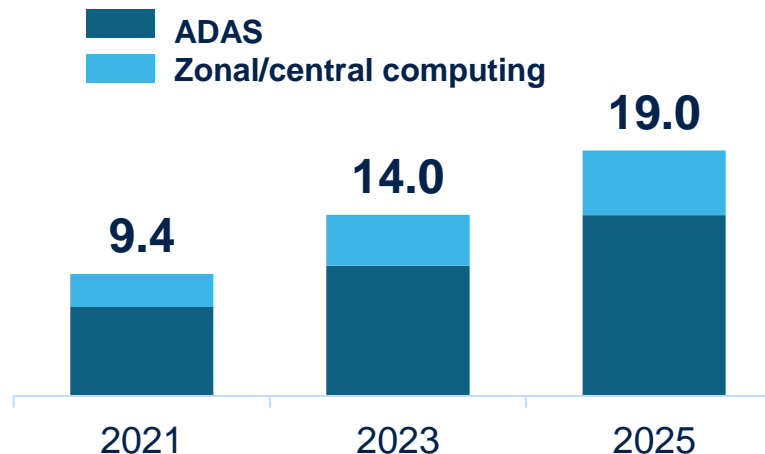


Vehicle electrification TAM [\$B]

## Software-defined vehicles



**+19%**  
CAGR 21-25

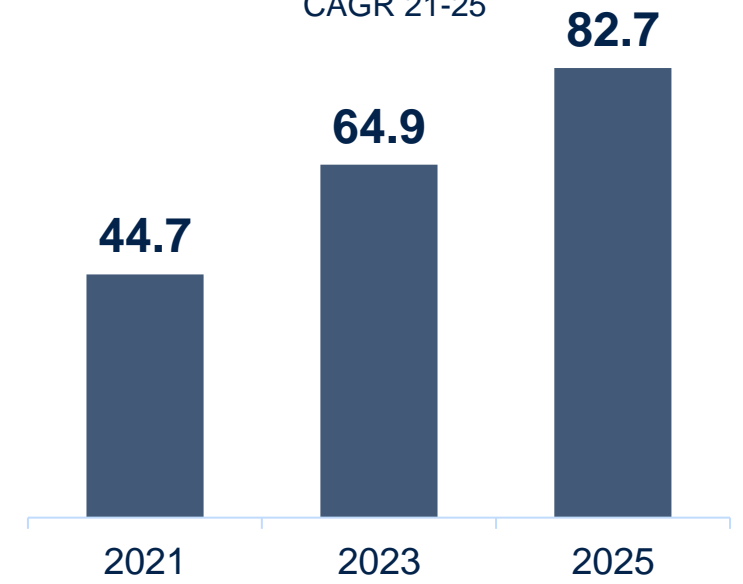


Vehicle digitalization TAM [\$B]

## Automotive TAM



**16.6%**  
CAGR 21-25

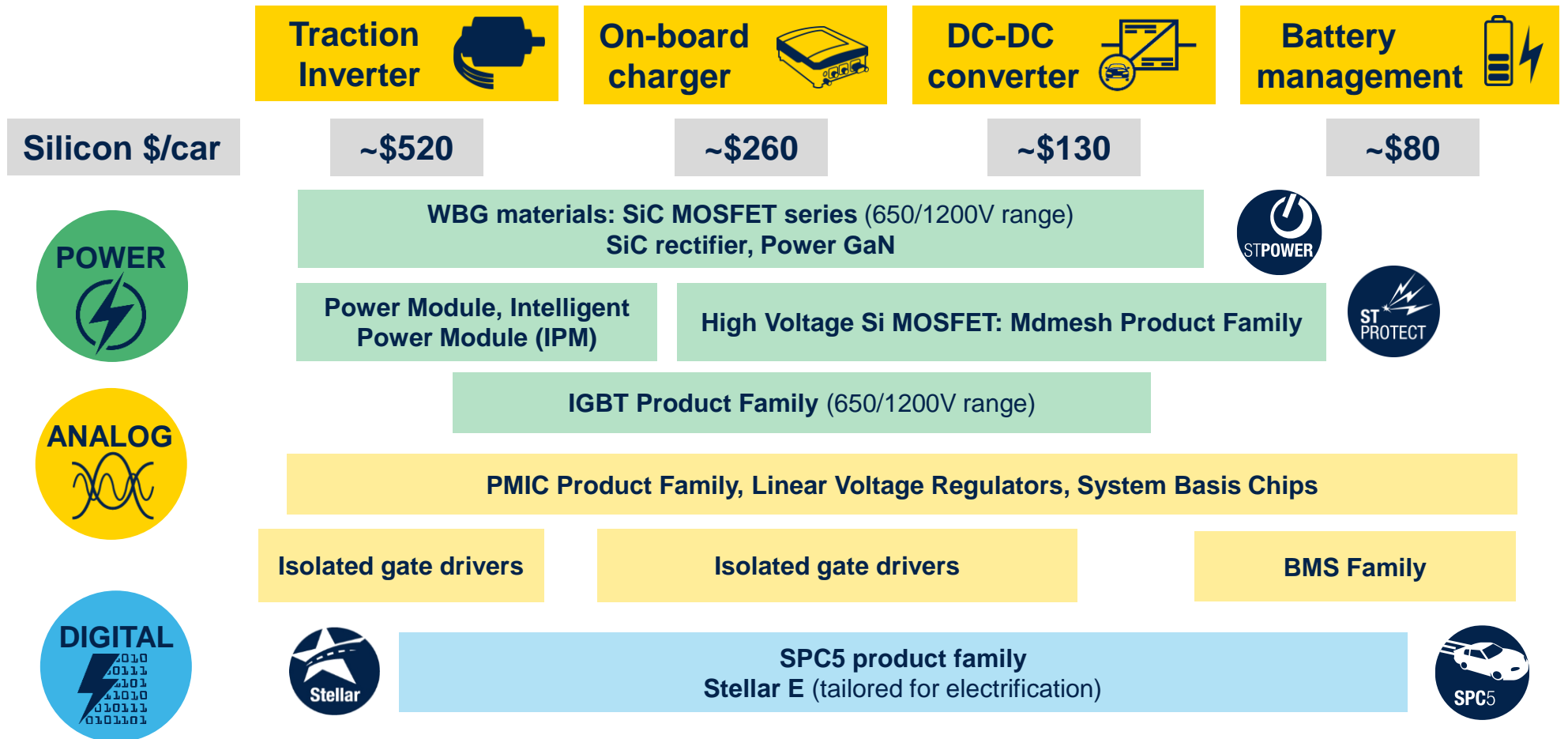


Overall automotive TAM [\$B]

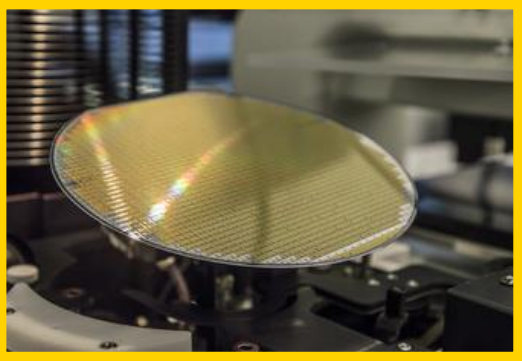
# ST leads in eMobility thanks to timely investment and a strong technology and product offering

**ST offers a truly broad range product portfolio for electrification based on state-of-the-art technologies**

ST anticipated the right technology development and capacity planning to serve the disruptive demands of eMobility



# ST silicon carbide focus areas



## Business Development

~\$500M revenue in 2021, >\$700M in 2022

> \$1B target anticipated in 2023 (75% Auto - 25% Industrial)

~80 customers, ~20 carmakers, ~100 programs awarded

## Fully integrated Manufacturing

SiC production-flow entirely mastered in-house

Dual sourcing: Singapore launched 2021 complementing Catania

New integrated 200 mm fab, ready by 2023 - 200 mm substrates, epitaxy and SiC MOSFETs

200 mm industrialization line in Catania to accelerate time to volumes

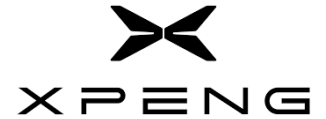
## Portfolio & Strategy

Portfolio of SiC MOSFETs & Diodes, & IGBT from 650V to 1700V

3<sup>rd</sup> Gen SiC MOSFETs in production, 4<sup>th</sup> in qualification, 5<sup>th</sup> planned with radical innovation thanks to a disruptive SiC trench concept

Flexible approach covering packages, modules, dice

# Solid silicon carbide customer base

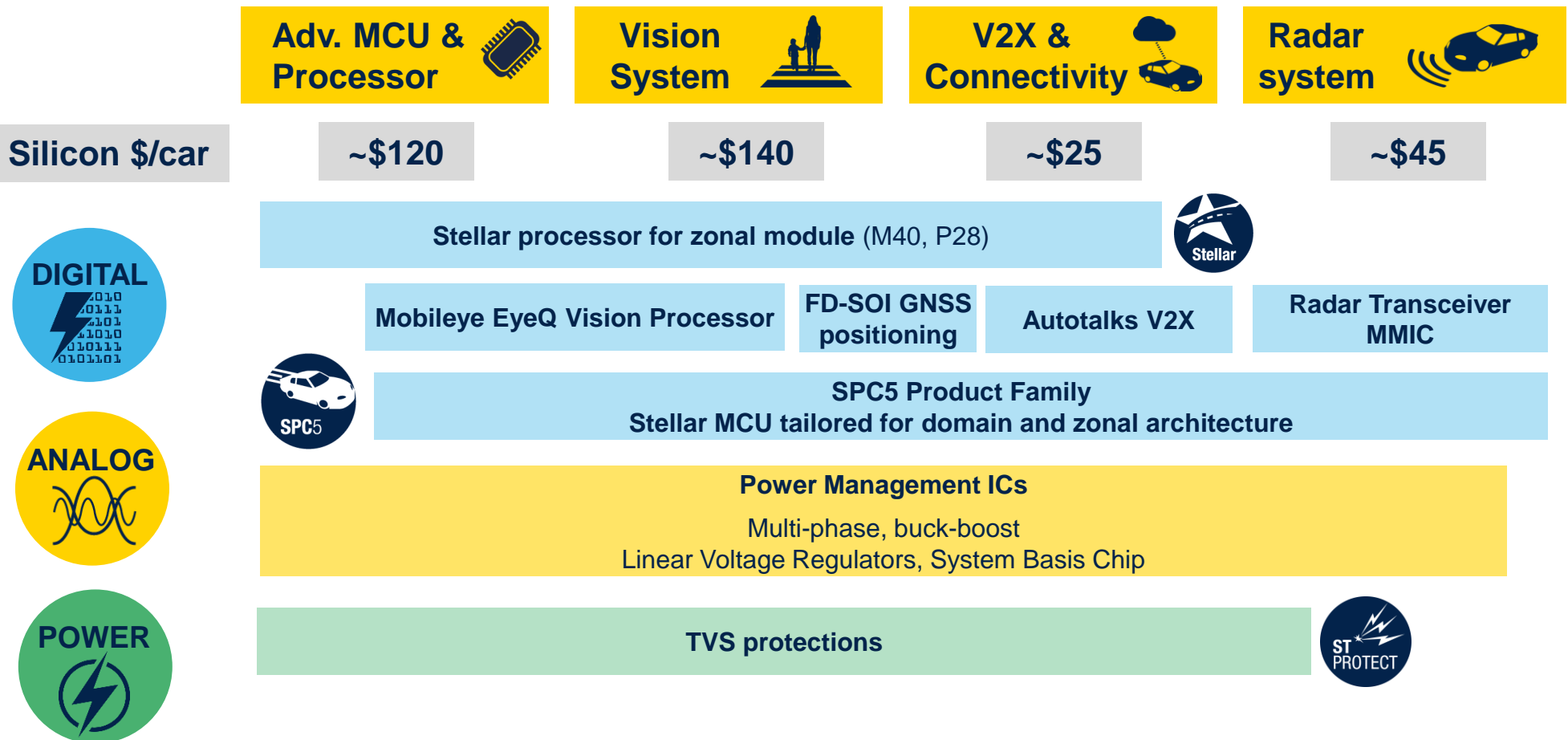




# ST meets the needs of the software-defined vehicle ADAS and new electrical/electronic architecture

Full system coverage with controllers, processors, sensors and power management meeting increased computation power requirements

Comprehensive ST product offer based on innovative technologies, efficient product development, long-lasting partnerships



# Long-standing partnership in ADAS with Mobileye



>100 Million EyeQ chips on the road

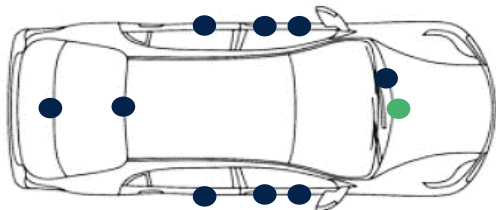
## EyeQ5 Family

High-end ADAS/AD\*\* partial

ADAS targeting L2++ → AD L4

7 nm, up to 26 DL Tops\*

- L2 front camera solution (1x EyeQ5M)
- Up to L4, partial/full surround (2x EyeQ5H)



In Production (SOP 2021)

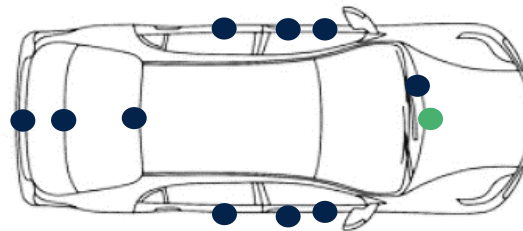
## EyeQ6 Family

Premium, high-efficiency ADAS/AD partial

ADAS & AD levels up to L4

7 nm single chip, 34 DL Tops

- L2+ front camera solution (1x EyeQ6L)
- Up to L4 partial/full surround (1x EyeQ6H)



SOP 2023

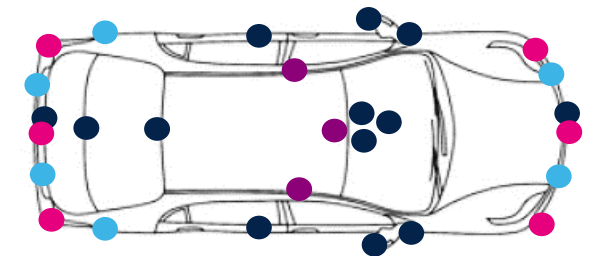
## EyeQ Ultra

Single SoC for end-to-end full AD

ADAS & AD levels up to L5

5 nm, 176 DL Tops

- 13 cameras
- 6 Short Range LiDARs
- 6 radar
- 3 Long Range LiDARs

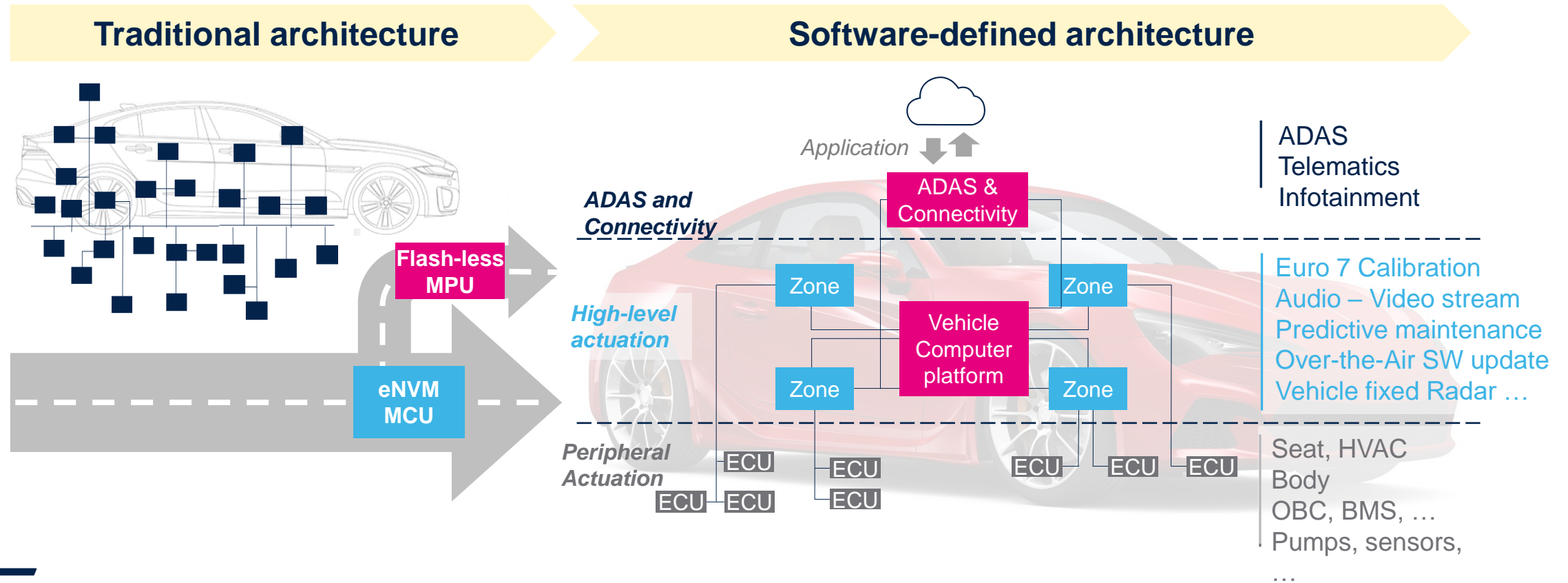


Prototypes for CES Jan 2024

Leading edge products capable to support the evolution of the system

# Software defined vehicles require a new architecture

New architecture requires both flash-less MPUs & eNVM\*-based MCUs to meet high computation requirements and real time control needs



\*eNVM embedded non-volatile memory

# Implications of SW-defined vehicle architectural change

## For car makers

### Enabling savings

- Optimized number of ECUs
- Harness cost and weight reduction
- SW cycle time and reuse

### Enabling new services

- Preventive maintenance
- Remote re-mapping (OTA)
- Upgradable SW functions
- New post-sales revenue streams

## For ST

### Strong increase in semiconductor content

Traditional architecture    X5 New car architecture

### Broad product offer

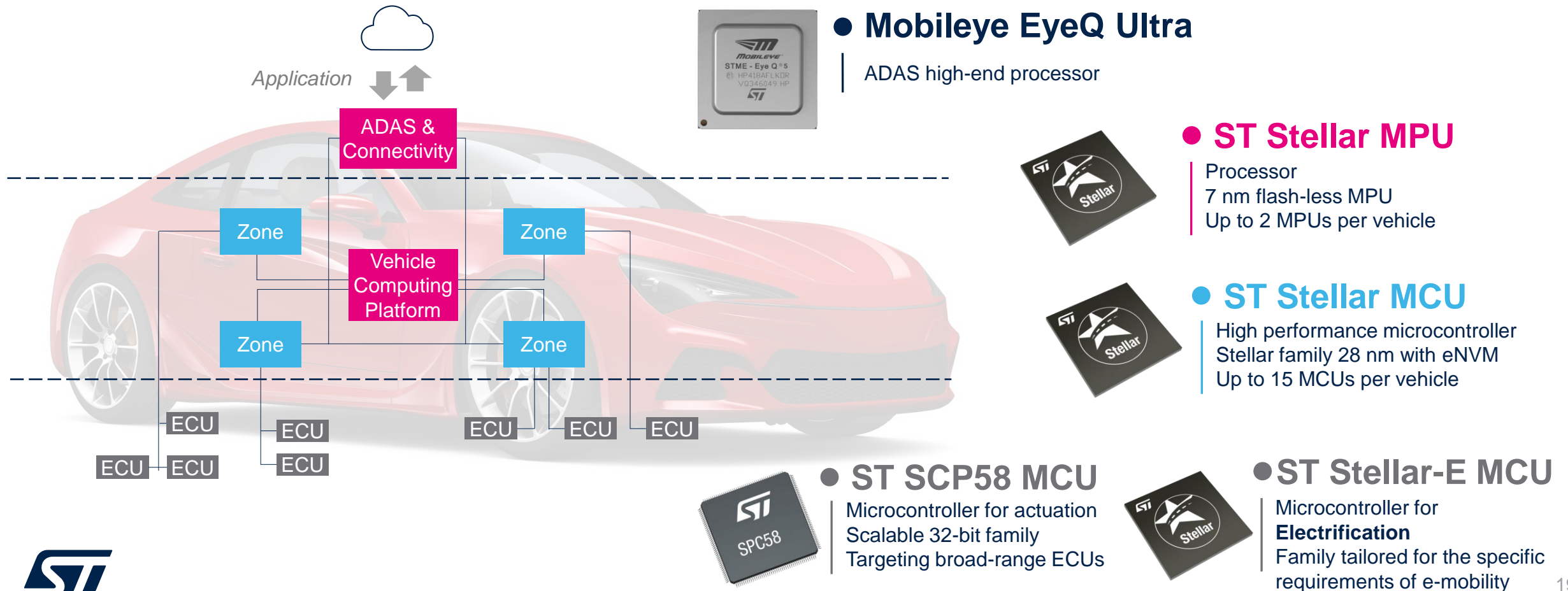
- MCU 28 nm FD-SOI with PCM for real-time control
- MPU 7 nm Flashless for computing platform
- Smart Power power management
- eFuse – fault tolerant systems smart protections



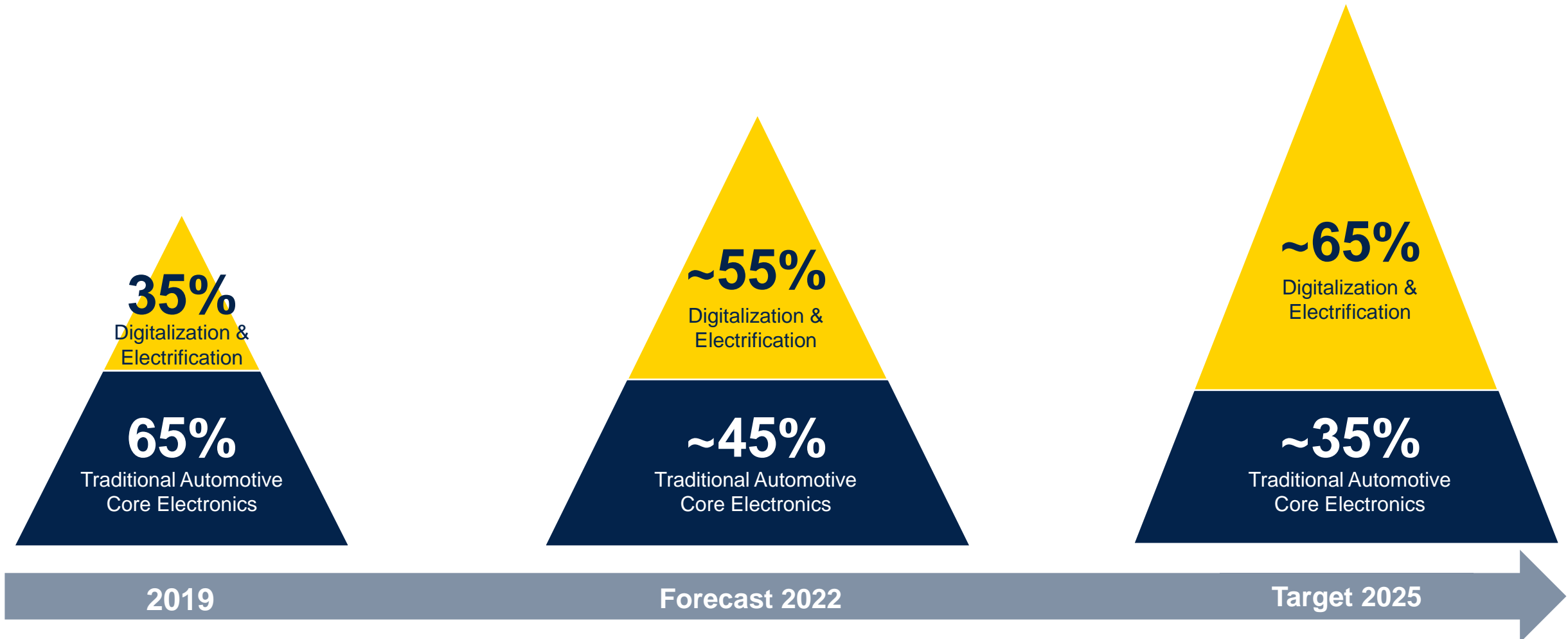
## Complementing ADAS node offer

# ST in the driving seat of the new car architecture

Full system coverage combining MPUs (7 nm FinFET) and MCUs (28 nm FD-SOI-ePCM / 40 nm eFlash)

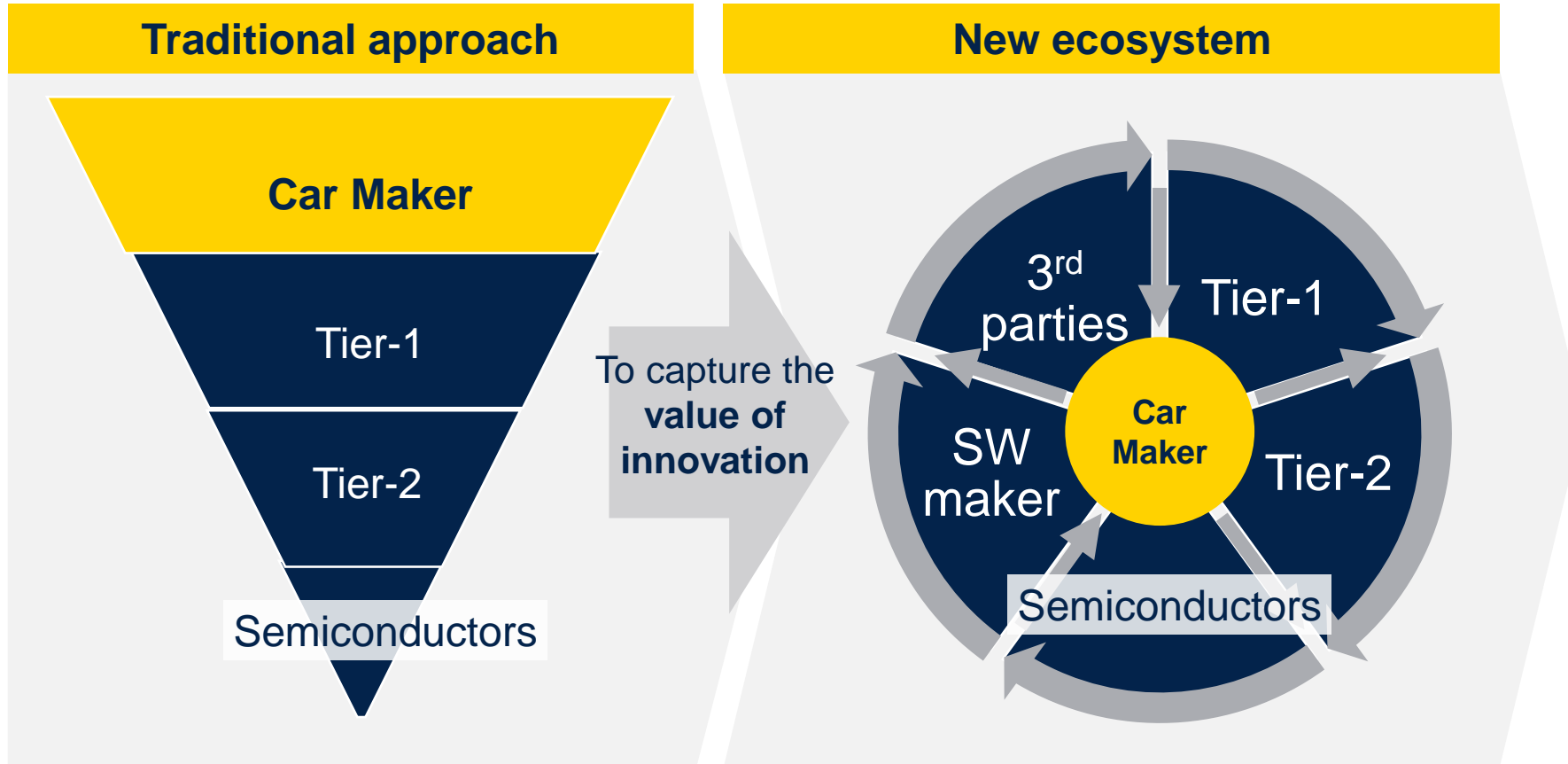


# ST is accelerating the transition to serve new mobility trends, consistent with our strategy





# Car makers becoming more centric in the semiconductor strategy

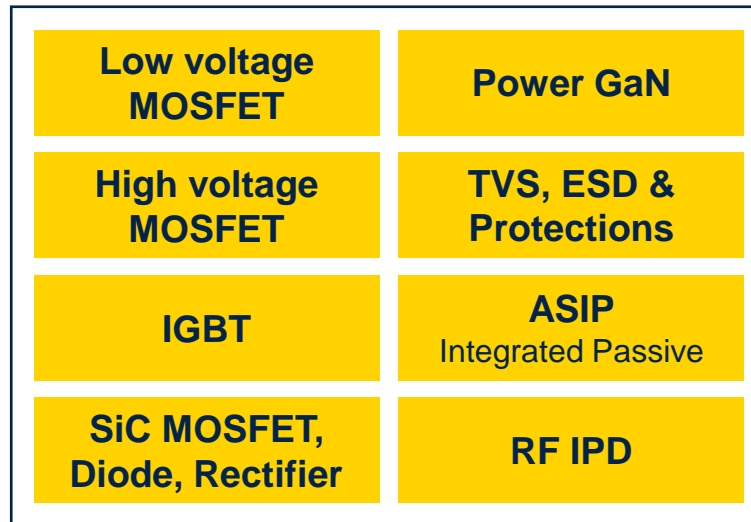
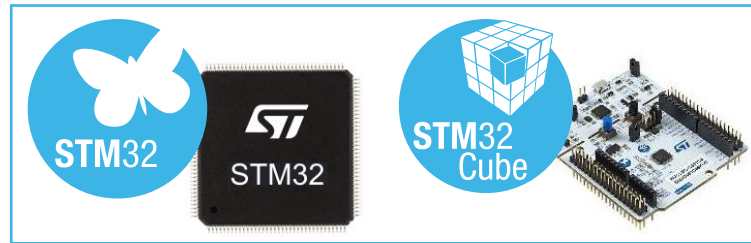
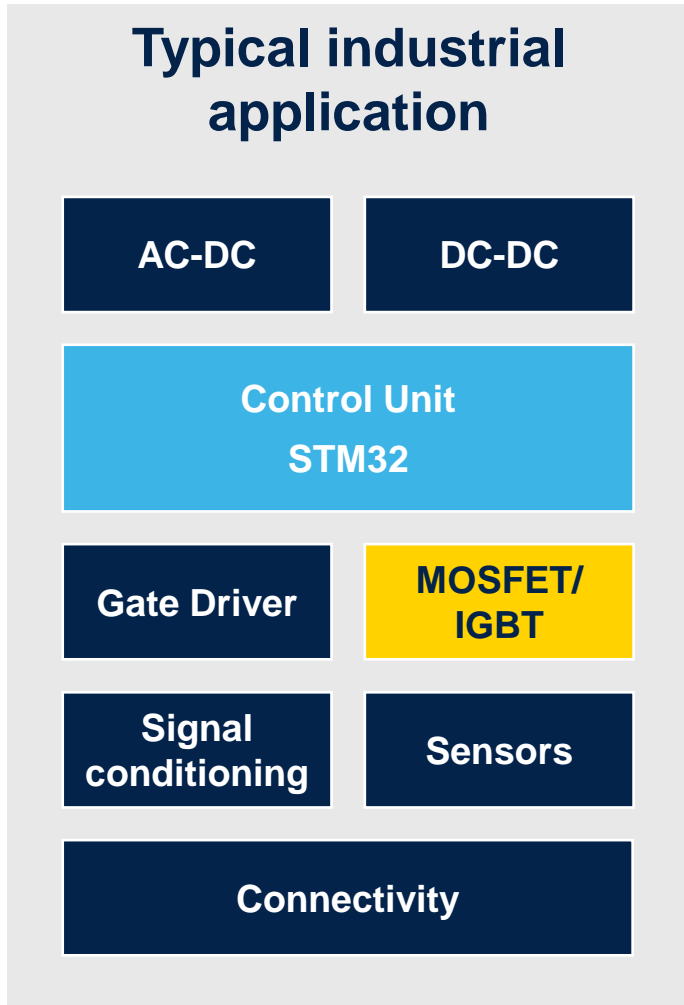


**From car makers to mobility provider**

Vehicle content and car differentiation strongly depend on semiconductors

**ST's is committed to play a major role in this new business model with multiple cooperations**

# Maximizing ST content in industrial applications



**Driving ST Growth**

Charging stations	STM32 \$6	ADG \$187
Factory automation	STM32 \$8.8	ADG \$19.6
Photovoltaics	STM32 \$17.1	ADG \$33.5
HVAC 2 kW	STM32 \$2.4	ADG \$10

Actual implementation based on selected customer products

# ST is developing a comprehensive GaN portfolio serving multiple markets

## ST Power GaN

Broad portfolio of discrete solutions leveraging flexible internal & external manufacturing



**Application coverage:** Power conversion systems for superior energy efficiency

**Main Markets:** Consumer first, while targeting high-value industrial (Solar Inverter, Charging pile...) and automotive (OBC, DC/DC...)

## ST RF-GaN

GaN-on-Silicon solution with competitive performance, cost & manufacturing scale vs GaN-on-SiC



**Application coverage:** 5G Power amplifiers

**Main Markets:** Telecom 5G Infrastructure and satellites (aerospace)

## Smart Integrated GaN

Advanced solutions integrating power stage and BCD driver & advanced control system (CMOS)



**GaN in CMOS**

**GaN in BCD**

**Application coverage:** DC-DC, LiDAR, class-D amplifiers

**Main Markets:** Automotive and industrial



# Supporting ST \$20B+ revenue ambition



Automotive silicon content is strongly increasing driven by multiple positive trends:

- Increased content of traditional applications
- Disruptive evolution to digitalization and electrification
- New and advanced features in modern vehicles

ST made early investments in innovation and manufacturing capabilities to serve the needs of the automotive industry  
Complete and innovative product offer  
Wide application coverage  
Extended network of partners

ADG innovation in power technologies and products is core to ST's strategy in industrial

# Our technology starts with You



Find out more at [www.st.com](http://www.st.com)

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